

ON Semiconductor®

## FDD6637-F085

# P-Channel PowerTrench $^{\circledR}$ MOSFET -35V, -21A, 18m $\Omega$

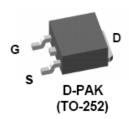
#### **Features**

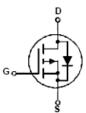
- Typ  $r_{DS(on)}$  = 9.7m $\Omega$  at  $V_{GS}$  = -10V,  $I_D$  =- 14A
- Typ  $r_{DS(on)}$  = 14.4m $\Omega$  at  $V_{GS}$  = -4.5V,  $I_D$  =- 11A
- Typ  $Q_{g(10)}$  = 45nC at  $V_{GS}$  = -10V
- High performance trench technology for extremely low r<sub>DS(on)</sub>.
- Qualified to AEC Q101
- RoHS Compliant

## **Applications**

- Inverter
- Power Supplies







## **MOSFET Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter		Ratings	Units
$V_{DSS}$	Drain to Source Voltage		-35	V
V <sub>DS(Avalanche)</sub>	Drain to Source Avalanche Voltage (maximum)		-45	V
V <sub>GS</sub>	Gate to Source Voltage		±25	V
1	Drain Current Continuous (T <sub>C</sub> < 155°C, V <sub>GS</sub> = 10V)		-21	Α
I <sub>D</sub>	Pulsed		See Figure 4	_ ^
E <sub>AS</sub>	Single Pulse Avalanche Energy (No	te 1)	61	mJ
D	Power Dissipation		68	W
$P_{D}$	Dreate above 25°C		0.46	W/oC
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature		-55 to + 175	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Maximum Thermal Resistance Junction to Case	2.2	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient TO-252, 1in <sup>2</sup> copper pad area	40	°C/W

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD6637	FDD6637-F085	TO-252	13"	12mm	2500 units

## **Electrical Characteristics** T<sub>C</sub> = 25°C unless otherwise noted

Parameter

Oπ Characteristics							
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	-35	-	-	V	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -28V, V_{GS} = 0V$	-	-	-1	μА	
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 25V$	-	-	±100	nA	

**Test Conditions** 

Min

Тур

Max

Units

#### **On Characteristics**

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1	-1.6	-3	V
		$I_D = -14A, V_{GS} = -10V$	-	9.7	11.6	
r <sub>DS(on)</sub>	Drain to Source On Resistance	I <sub>D</sub> = -11A, V <sub>GS</sub> = -4.5V	-	14.4	18	$m\Omega$
		$I_D = -14A$ , $V_{GS} = -10V$ , $T_C = 150$ °C	-	15.3	18	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -5V, I <sub>D</sub> = -14A	-	35	-	S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 00V V	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, -f = 1MHz		2370	-	pF
C <sub>oss</sub>	Output Capacitance				470	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1101112			250	-	pF
$R_G$	Gate Resistance	f = 1MHz	f = 1MHz		3.6	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at -10V	$V_{GS} = 0 \text{ to } -10V$		-	45	63	nC
$Q_{g(5)}$	Total Gate Charge at -5V	$V_{GS} = 0 \text{ to } -5V$	V <sub>DD</sub> = -20V	-	25	35	nC
$Q_{gs}$	Gate to Source Gate Charge		I <sub>D</sub> = -14A	-	7	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge			-	10	-	nC

<b>Electrical Characteristics</b>	$T_C = 25^{\circ}C$ unless otherwise noted
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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	18	32	ns
t <sub>r</sub>	Rise Time	$V_{DD} = -20V, I_D = -1A,$	-	10	20	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = -10V$ , $R_{GEN} = 6\Omega$	-	62	100	ns
t <sub>f</sub>	Fall Time		1	36	58	ns

#### **Drain-Source Diode Characteristics**

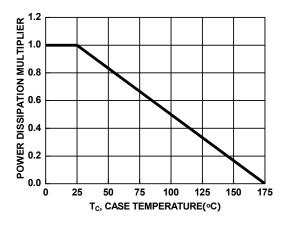
$V_{SD}$	Source to Drain Diode Voltage	I <sub>SD</sub> = -14A	-	-0.8	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	-I <sub>F</sub> = -14A, dI <sub>SD</sub> /dt = 100A/μs	-	28	37	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	15	20	nC

#### Notes:

1: Starting  $T_J = 25^{\circ}C$ , L = 1mH,  $I_{AS} = -11$ A,  $V_{GS} = 10$ V,  $V_{DD} = -35$ V during the inductor charging time and 0V during the time in avalanche

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/

#### **Typical Characteristics**



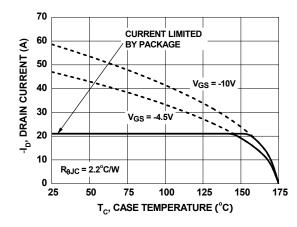
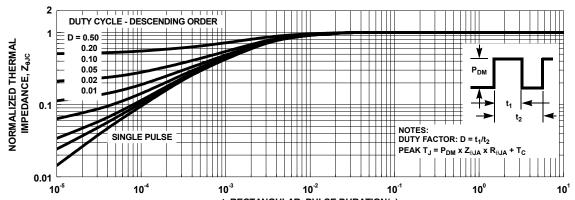


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

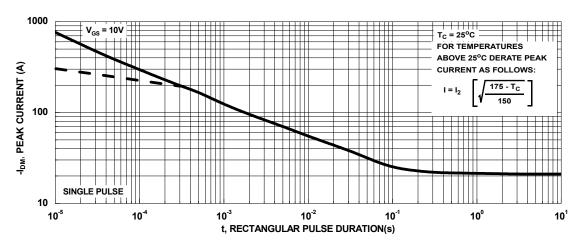


Figure 4. Peak Current Capability

## **Typical Characteristics**

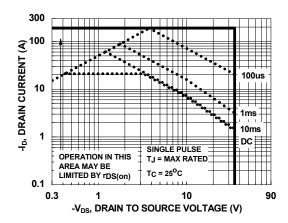
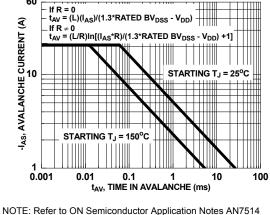


Figure 5. Forward Bias Safe Operating Area



60

and AN7515

Figure 6. Unclamped Inductive Switching Capability

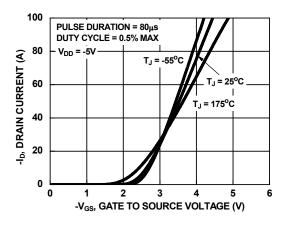


Figure 7. Transfer Characteristics

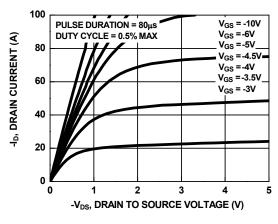


Figure 8. Saturation Characteristics

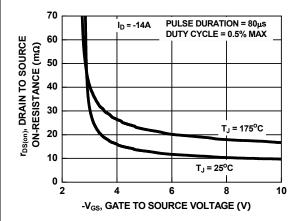


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

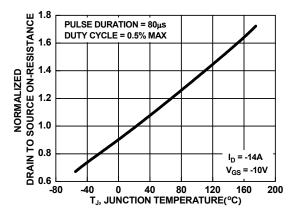


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

## **Typical Characteristics**

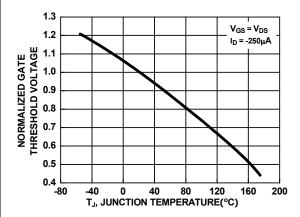


Figure 11. Normalized Gate Threshold Voltage vs
Junction Temperature

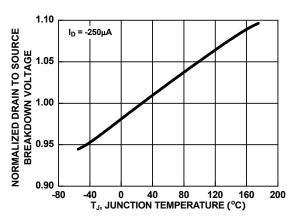


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

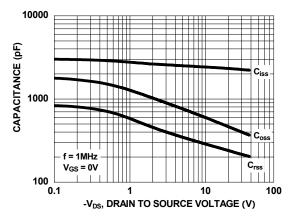


Figure 13. Capacitance vs Drain to Source Voltage

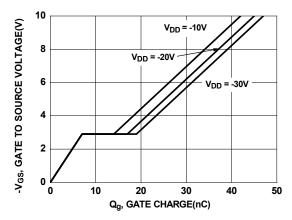


Figure 14. Gate Charge vs Gate to Source Voltage

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